

INFORMATION NOTE



N° 006/12

Implementation of a packing belt for all QFP – packages with 100 & above leaded tape assembled at Infineon Technologies, Malaysia.

Subject of Change: Implementation of a packing belt for all QFP – packages with 100 & above leaded tape assembled at Infineon Technologies, Malaysia.

Products affected: All products assembled in QFP - packages at Infineon Technologies (Malaysia) Sdn. Bhd., Malacca as listed per Sales Code in attached document 1_cip12006.

Reason of Change: In order to improve the packing robustness Infineon will implement the packing belt.

DESCRIPTION OF CHANGE:	<u>OLD</u>	<u>NEW</u>
<ul style="list-style-type: none">■ Packing belt introduction:	Products affected delivered <u>without</u> packing belt.	Products affected delivered <u>with</u> packing belt.  Packing belt

Assessment: No change in fit, form function and reliability.

Time schedule: From February 2014 onwards.

Documentation: 1_cip12006: Products affected

If you have any questions, please do not hesitate to contact your local Sales office.